Bambu Filament Guide

This filament guide offers a comprehensive comparison of properties, application, and printing requirements for Bambu filaments, aiming to help users select the best-suited material for needs.For detailed technical information, download filament Technical data sheets (TDS) on product pages

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Basic Information	Filament Properties										Pre-printing Preparation						Printer Settings					Post-printing Processes
Filament	Toughness (Impact Strength - XY)	Strength (Bending Strength - XY)	Stiffness (Bending Modulus - XY)	Layer Adhesion (Impact Strength - Z)	Heat Resistance (HDT, 0.45 MPa)	Saturated Water Absorption Rate (25 ℃, 65% RH)	Shore Hardness	Rebound Resilience	Strength (Tensile Strength - XY)	Layer Adhesion (Tear Strength - Z)	Dry Out Before Use	Drying Condition	AMS Compatibility	Nozzle Size/Material	Build Plate & Bed Temperature	Adhesion Methods	Print with Enclosure	Seal with Desiccant	Print Speed	Nozzle Temperature	Part Cooling Fan	Annealing*
PLA Basic	26.6 kJ/m²	76 MPa	2750 MPa	13.8 kJ/m²	57 ℃	0.43%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 50 ℃, 8 h Printer Heatbed (Covered, Flip midway): 60 - 70 ℃, 12 h	✔	All Size/Material	Cool Plate (35 - 55 ℃) Smooth PEI Plate (55 - 65 ℃) Textured PEI Plate (55 - 65 ℃) Cool Plate SuperTack (30 - 45 ℃)	No glue required	Not required	Not required	< 300 mm/s	190 - 230 ℃	50% - 100%	50 - 60 ℃ 6 - 12 hours
PLA Lite	19.0 kJ/m²	51 MPa	2240 MPa	6 kJ/m²	60 ℃	0.26%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 50 ℃, 8 h Printer Heatbed (Covered, Flip midway): 60 - 70 ℃, 12 h	✔	All Size/Material	Cool Plate (35 - 55 ℃) Smooth PEI Plate (55 - 65 ℃) Textured PEI Plate (55 - 65 ℃) Cool Plate SuperTack (30 - 45 ℃)	No glue required	Not required	Not required	< 250 mm/s	190 - 240 ℃	On	50 - 60 ℃ 6 - 12 hours
PLA Matte	19.2 kJ/m²	53 MPa	2360 MPa	6.6 kJ/m²	58 ℃	0.40%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 50 ℃, 8 h Printer Heatbed (Covered, Flip midway): 60 - 70 ℃, 12 h	✔	All Size/Material	Cool Plate (35 - 55 ℃) Smooth PEI Plate (55 - 65 ℃) Textured PEI Plate (55 - 65 ℃) Cool Plate SuperTack (30 - 45 ℃)	No glue required	Not required	Not required	< 300 mm/s	190 - 230 ℃	On	50 - 60 ℃ 6 - 12 hours
PLA Silk	24.5 kJ/m²	66 MPa	2370 MPa	4.6 kJ/m²	53 ℃	0.52%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 55 ℃, 8 h Printer Heatbed (Covered, Flip midway): 65 - 75 ℃, 12 h	✔	All Size/Material	Cool Plate (35 - 55 ℃) Smooth PEI Plate (55 - 65 ℃) Textured PEI Plate (55 - 65 ℃)	No glue required	Not required	Not required	< 250 mm/s	210 - 240 ℃	On	50 - 60 ℃ 6 - 12 hours
PLA Silk+	18.5 kJ/m²	75 MPa	2460 MPa	8.5 kJ/m²	60 ℃	0.40%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 55 ℃, 8 h Printer Heatbed (Covered, Flip midway): 65 - 75 ℃, 12 h	✔	All Size/Material	Cool Plate (35 - 55 ℃) Smooth PEI Plate (55 - 65 ℃) Textured PEI Plate (55 - 65 ℃) Cool Plate SuperTack (30 - 45 ℃)	No glue required	Not required	Not required	< 250 mm/s	210 - 240 ℃	On	50 - 60 ℃ 6 - 12 hours
PLA Metal	58.9 kJ/m²	66 MPa	2290 MPa	16.8 kJ/m²	62 ℃	0.40%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 55 ℃, 8 h Printer Heatbed (Covered, Flip midway): 65 - 75 ℃, 12 h	✔	All Size/Material	Cool Plate (35 - 55 ℃) Smooth PEI Plate (55 - 65 ℃) Textured PEI Plate (55 - 65 ℃) Cool Plate SuperTack (30 - 45 ℃)	No glue required	Not required	Not required	< 300 mm/s	190 - 230 ℃	On	50 - 60 ℃ 6 - 12 hours
PLA Sparkle	66.5 kJ/m²	63 MPa	2310 MPa	10.3 kJ/m²	55 ℃	0.44%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 55 ℃, 8 h Printer Heatbed (Covered, Flip midway): 65 - 75 ℃, 12 h	✔	0.4 / 0.6 / 0.8 mm Hardened Steel	Cool Plate (35 - 55 ℃) Smooth PEI Plate (55 - 65 ℃) Textured PEI Plate (55 - 65 ℃) Cool Plate SuperTack (30 - 45 ℃)	No glue required	Not required	Not required	< 250 mm/s	190 - 230 ℃	On	50 - 60 ℃ 6 - 12 hours
PLA Galaxy	55.4 kJ/m²	58 MPa	2200 MPa	5.8 kJ/m²	55 ℃	0.45%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 55 ℃, 8 h Printer Heatbed (Covered, Flip midway): 65 - 75 ℃, 12 h	✔	All Size/Material	Cool Plate (35 - 55 ℃) Smooth PEI Plate (55 - 65 ℃) Textured PEI Plate (55 - 65 ℃) Cool Plate SuperTack (30 - 45 ℃)	No glue required	Not required	Not required	< 250 mm/s	190 - 230 ℃	On	50 - 60 ℃ 6 - 12 hours
PLA Wood	15.7 kJ/m²	55 MPa	2780 MPa	5.6 kJ/m²	60 ℃	1.25%	N/A	N/A	N/A	N/A	Required	Blast Drying Oven: 55 ℃, 8 h Printer Heatbed (Covered, Flip midway): 65 - 75 ℃, 12 h	✔	0.4 / 0.6 / 0.8 mm Hardened Steel / Stainless Steel	Cool Plate (35 - 55 ℃) Smooth PEI Plate (55 - 65 ℃) Textured PEI Plate (55 - 65 ℃) Cool Plate SuperTack (30 - 45 ℃)	No glue required	Not required	Required	< 250 mm/s	190 - 240 ℃	On	50 - 60 ℃ 6 - 12 hours
PLA Marble	24.0 kJ/m²	75 MPa	2920 MPa	6.5 kJ/m²	56 ℃	0.44%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 55 ℃, 8 h Printer Heatbed (Covered, Flip midway): 65 - 75 ℃, 12 h	✔	0.4 / 0.6 / 0.8 mm Hardened Steel / Stainless Steel	Cool Plate (35 - 55 ℃) Smooth PEI Plate (55 - 65 ℃) Textured PEI Plate (55 - 65 ℃) Cool Plate SuperTack (30 - 45 ℃)	No glue required	Not required	Not required	< 250 mm/s	190 - 230 ℃	On	50 - 60 ℃ 6 - 12 hours
PLA Translucent	18.5 kJ/m²	85 MPa	3000 MPa	8.5 kJ/m²	60 ℃	0.34%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 50 ℃, 8 h Printer Heatbed (Covered, Flip midway): 60 - 70 ℃, 12 h	✔	All Size/Material	Cool Plate (35 - 55 ℃) Smooth PEI Plate (55 - 65 ℃) Textured PEI Plate (55 - 65 ℃) Cool Plate SuperTack (30 - 45 ℃)	No glue required	Not required	Not required	< 150 mm/s	200 - 240 ℃	On	50 - 60 ℃ 6 - 12 hours
PLA Tough+	80.6 kJ/m²	65 MPa	2140 MPa	25.9 kJ/m²	61 ℃	0.27%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 50 ℃, 8 h Printer Heatbed (Covered, Flip midway): 60 - 70 ℃, 12 h	✔	All Size/Material	Cool Plate (35 - 55 ℃) Smooth PEI Plate (55 - 65 ℃) Textured PEI Plate (55 - 65 ℃) Cool Plate SuperTack (30 - 45 ℃)	No glue required	Not required	Not required	< 300 mm/s	220 - 250 ℃	On	50 - 60 ℃ 6 - 12 hours
PLA Glow	27.3 kJ/m²	76 MPa	2640 MPa	19.8 kJ/m²	55 ℃	0.46%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 55 ℃, 8 h Printer Heatbed (Covered, Flip midway): 65 - 75 ℃, 12 h	✔	0.4 / 0.6 / 0.8 mm Hardened Steel / Stainless Steel	Cool Plate (35 - 55 ℃) Smooth PEI Plate (55 - 65 ℃) Textured PEI Plate (55 - 65 ℃) Cool Plate SuperTack (30 - 45 ℃)	No glue required	Not required	Not required	< 250 mm/s	190 - 230 ℃	On	50 - 60 ℃ 6 - 12 hours
PLA Aero	28.8 kJ/m²	45 MPa	1690 MPa	3.1 kJ/m²	53 ℃	0.45%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 55 ℃, 8 h Printer Heatbed (Covered, Flip midway): 65 - 75 ℃, 12 h	✔	0.4 / 0.6 / 0.8 mm Hardened Steel / Stainless Steel	Cool Plate (35 - 55 ℃) Smooth PEI Plate (55 - 65 ℃) Textured PEI Plate (55 - 65 ℃)	No glue required	Not required	Not required	< 180 mm/s	210 - 260 ℃	On	Not recommended. If required: 50 - 55 ℃. 6 - 12 hours
PLA Pure	20.6 kJ/m²	75 MPa	2880 MPa	10.0 kJ/m²	60 ℃	0.28%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 50 ℃, 8 h Printer Heatbed (Covered, Flip midway): 60 - 70 ℃, 12 h	✔	All Size/Material	Cool Plate (35 - 55 ℃) Smooth PEI Plate (55 - 65 ℃) Textured PEI Plate (55 - 65 ℃) Cool Plate SuperTack (30 - 45 ℃)	Not recommended (The use of glue may affect the electrical contact reliability of the final product. Increasing the bed temperature appropriately can improve adhesion)	Not required	Not required	< 200 mm/s	190 - 230 ℃	On	50 - 60 ℃ 6 - 12 hours
PLA-CF	23.2 kJ/m²	89 MPa	3950 MPa	7.8 kJ/m²	55 ℃	0.42%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 55 ℃, 8 h Printer Heatbed (Covered, Flip midway): 65 - 75 ℃, 12 h	✔	0.4 / 0.6 (recommended) / 0.8 mm Hardened Steel	Cool Plate (45 - 55 ℃) Smooth PEI Plate (55 - 65 ℃) Textured PEI Plate (55 - 65 ℃) Cool Plate SuperTack (50 - 55 ℃)	No glue required	Not required	Not required	< 200 mm/s	210 - 240 ℃	On	55 - 60 ℃ 6 - 12 hours
Support for PLA	N/A	N/A	N/A	N/A	N/A	0.88%	N/A	N/A	N/A	N/A	Required	Blast Drying Oven: 55 ℃, 8 h Printer Heatbed (Covered, Flip midway): 65 - 75 ℃, 12 h	✔	All Size/Material	Cool Plate (40 - 55 ℃) Smooth PEI Plate (55 - 65 ℃) Textured PEI Plate (55 - 65 ℃) Cool Plate SuperTack (30 - 45 ℃)	No glue required	Not required	Not required	< 200 mm/s	220 - 230 ℃	On	N/A
PETG Basic	34.2 kJ/m²	75 MPa	1950 MPa	10.5 kJ/m²	71 ℃	0.45%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 65 ℃, 8 h Printer Heatbed (Covered, Flip midway): 80 ℃, 12 h	✔	All Size/Material	Smooth PEI Plate (65 - 75 ℃) Textured PEI Plate (65 - 75 ℃) Cool Plate SuperTack (65 - 75 ℃)	Bambu Liquid Glue / Glue Stick recommended	Not required	Not required	< 200 mm/s	230 - 260 ℃	0 - 60%	Not recommended. If required: 60 - 70 ℃. 4 - 8 hours
PETG Matte	32.6 kJ/m²	65 MPa	1995 MPa	10.0 kJ/m²	72.3 ℃	0.29%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 65 ℃, 8 h Printer Heatbed (Covered, Flip midway): 80 ℃, 12 h	✔	All Size/Material	Cool Plate (40 - 55 ℃) Smooth PEI Plate (55 - 65 ℃) Textured PEI Plate (55 - 65 ℃) Cool Plate SuperTack (40 - 45 ℃)	Bambu Liquid Glue / Glue Stick recommended	Not required	Not required	< 250 mm/s	230 - 260 ℃	Off	60 - 70 ℃ 6 - 12 hours
PETG Translucent	37.4 kJ/m²	68 MPa	1610 MPa	7.2 kJ/m²	74 ℃	0.30%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 65 ℃, 8 h Printer Heatbed (Covered, Flip midway): 75 - 85 ℃, 12 h	✔	All Size/Material	Smooth PEI Plate (65 - 75 ℃) Textured PEI Plate (65 - 75 ℃) Cool Plate SuperTack (60 - 75 ℃)	Bambu Liquid Glue / Glue Stick recommended	Not required	Not required	< 220 mm/s	230 - 270 ℃	0 - 60%	Not recommended. If required: 60 - 70 ℃. 4 - 8 hours
PETG-CF	41.2 kJ/m²	70 MPa	2910 MPa	10.7 kJ/m²	74 ℃	0.30%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 65 ℃, 8 h Printer Heatbed (Covered, Flip midway): 75 - 85 ℃, 12 h	✔	0.4 / 0.6 / 0.8 mm Hardened Steel	Smooth PEI Plate (60 - 80 ℃) Textured PEI Plate (60 - 80 ℃) Cool Plate SuperTack (60 - 70 ℃)	Bambu Liquid Glue / Glue Stick recommended	Not required	Required	< 200 mm/s	240 - 270 ℃	0 - 40%	65 - 70 ℃ 6 - 12 hours
Support for PLA/PETG	N/A	N/A	N/A	N/A	N/A	1.02%	N/A	N/A	N/A	N/A	Required	Blast Drying Oven: 75 ℃, 8 h Printer Heatbed (Covered, Flip midway): 65 - 75 ℃, 12 h	✔	All Size/Material	Cool Plate (35 - 55 ℃) Smooth PEI Plate (60 - 70 ℃) Textured PEI Plate (60 - 70 ℃)	No glue required	Not required	Required	< 100 mm/s	190 - 220 ℃	On	N/A
PVA	N/A	N/A	N/A	N/A	N/A	6.25%	N/A	N/A	N/A	N/A	Required	Blast Drying Oven: 80 ℃, 8 - 12 h Printer Heatbed (Covered, Flip midway): 90 - 100 ℃, 12 h	✔	0.4 / 0.6 / 0.8 mm Hardened Steel / Stainless Steel	Cool Plate (35 - 45 ℃) Smooth PEI Plate (35 - 45 ℃) Textured PEI Plate (35 - 45 ℃) Cool Plate SuperTack (35 - 45 ℃)	No glue required	Not required	Required	< 200 mm/s	220 - 250 ℃	On	N/A
ABS	39.3 kJ/m²	62 MPa	1880 MPa	7.4 kJ/m²	87 ℃	0.65%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 80 ℃, 8 h Printer Heatbed (Covered, Flip midway): 90 - 100 ℃, 12 h	✔	All Size/Material	Smooth PEI Plate (90 - 100 ℃) Textured PEI Plate (90 - 100 ℃)	Bambu Liquid Glue / Glue Stick required	Required	Not required	< 300 mm/s	240 - 280 ℃	0 - 80%	80 - 90 ℃ 6 - 12 hours
ABS-GF	14.5 kJ/m²	68 MPa	2860 MPa	5.3 kJ/m²	99 ℃	0.53%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 80 ℃, 8 h Printer Heatbed (Covered, Flip midway): 90 - 100 ℃, 12 h	✔	0.4 / 0.6 (recommended) / 0.8 mm Hardened Steel	Smooth PEI Plate (90 - 100 ℃) Textured PEI Plate (90 - 100 ℃)	Bambu Liquid Glue required	Required	Not required	< 180 mm/s	240 - 280 ℃	0 - 80%	80 - 90 ℃ 6 - 12 hours
Support for ABS	N/A	N/A	N/A	N/A	N/A	0.14%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 80 ℃, 4 h Printer Heatbed (Covered, Flip midway): 85 - 95 ℃, 6 h	✔	0.4 / 0.6 / 0.8 mm Hardened Steel / Stainless Steel	Smooth PEI Plate (80 - 100 ℃) Textured PEI Plate (80 - 100 ℃)	Bambu Liquid Glue / Glue Stick required	Required	Not required	< 100 mm/s	240 - 270 ℃	On	N/A
ASA	41.0 kJ/m²	65 MPa	1920 MPa	4.9 kJ/m²	100 ℃	0.45%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 80 ℃, 8 h Printer Heatbed (Covered, Flip midway): 90 - 100 ℃, 12 h	✔	All Size/Material	Smooth PEI Plate (90 - 100 ℃) Textured PEI Plate (90 - 100 ℃)	Bambu Liquid Glue / Glue Stick required	Required	Not required	< 250 mm/s	240 - 280 ℃	0 - 80%	80 - 90 ℃ 6 - 12 hours
ASA Aero	32.0 kJ/m²	58 MPa	1510 MPa	3.4 kJ/m²	85 ℃	0.80%	N/A	N/A	N/A	N/A	Required	Blast Drying Oven: 80 ℃, 8 h Printer Heatbed (Covered, Flip midway): 90 - 100 ℃, 12 h	✔	0.4 (recommended) / 0.6 / 0.8 mm Hardened Steel / Stainless Steel	Smooth PEI Plate (80 - 90 ℃) Textured PEI Plate (80 - 90 ℃)	Bambu Liquid Glue / Glue Stick required	Required	Required	< 150 mm/s	240 - 280 ℃	0 - 80%	80 - 90 ℃ 6 - 12 hours
ASA-CF	14.0 kJ/m²	72 MPa	3740 MPa	9.4 kJ/m²	110 ℃	0.33%	N/A	N/A	N/A	N/A	Optional	Blast Drying Oven: 80 ℃, 8 h Printer Heatbed (Covered, Flip midway): 90 - 100 ℃, 12 h	✔	0.4 / 0.6 / 0.8 mm Hardened Steel	Smooth PEI Plate (90 - 100 ℃) Textured PEI Plate (90 - 100 ℃)	Bambu Glue Stick required	Required	Not required	< 250 mm/s	250 - 290 ℃	0 - 80%	80 - 90 ℃ 6 - 12 hours
PC	34.8 kJ/m²	108 MPa	2310 MPa	9.0 kJ/m²	117 ℃	0.25%	N/A	N/A	N/A	N/A	Required	Blast Drying Oven: 80 ℃, 8 h Printer Heatbed (Covered, Flip midway): 90 - 100 ℃, 12 h	✔	All Size/Material	Smooth PEI Plate (90 - 110 ℃) Textured PEI Plate (90 - 110 ℃)	Bambu Glue Stick required	Required	Required	< 300 mm/s	260 - 280 ℃	0 - 60%	85 - 100 ℃ 6 - 12 hours
PC FR	55.0 kJ/m²	90 MPa	1890 MPa	8.0 kJ/m²	113 ℃	0.12%	N/A	N/A	N/A	N/A	Required	Blast Drying Oven: 80 ℃, 8 h Printer Heatbed (Covered, Flip midway): 90 - 100 ℃, 12 h	✔	All Size/Material	Smooth PEI Plate (90 - 110 ℃) Textured PEI Plate (90 - 110 ℃)	Bambu Glue Stick required	Required	Required	< 300 mm/s	260 - 280 ℃	0 - 60%	85 - 100 ℃ 6 - 12 hours
TPU 75A	N/A	N/A	N/A	N/A	N/A	0.70%	76 A	50%	11.5 MPa	14.0 N/mm	Required	Blast Drying Oven: 70 ℃, 8 h Printer Heatbed (Covered, Flip midway): 90 ℃, 16 h		0.4 / 0.6 / 0.8 mm Hardened Steel / Stainless Steel	Smooth PEI Plate (30 - 35 ℃) Textured PEI Plate (30 - 35 ℃)	No glue required	Not required	Required	< 200 mm/s	200 - 250 ℃	On	N/A
TPU 85A	N/A	N/A	N/A	N/A	N/A	0.67%	84 A	42%	20.8 MPa	8.1 N/mm	Required	Blast Drying Oven: 70 ℃, 8 h Printer Heatbed (Covered, Flip midway): 90 ℃, 16 h		0.6 / 0.8 mm Hardened Steel / Stainless Steel	Smooth PEI Plate (30 - 35 ℃) Textured PEI Plate (30 - 35 ℃)	No glue required	Not required	Required	< 80 mm/s	200 - 250 ℃	50% - 100%	N/A
TPU 90A	N/A	N/A	N/A	N/A	N/A	0.61%	89 A	34%	25.5 MPa	12.3 N/mm	Required	Blast Drying Oven: 70 ℃, 8 h Printer Heatbed (Covered, Flip midway): 90 ℃, 16 h		0.4 / 0.6 / 0.8 mm Hardened Steel / Stainless Steel	Smooth PEI Plate (30 - 35 ℃) Textured PEI Plate (30 - 35 ℃)	No glue required	Not required	Required	< 80 mm/s	200 - 250 ℃	50% - 100%	N/A
TPU 95A HF	N/A	N/A	N/A	N/A	N/A	1.08%	92 A	30%	28.9 MPa	21.1 N/mm	Required	Blast Drying Oven: 70 ℃, 8 h Printer Heatbed (Covered, Flip midway): 80 - 90 ℃, 12 h		0.4 / 0.6 / 0.8 mm Hardened Steel / Stainless Steel	Smooth PEI Plate (30 - 35 ℃) Textured PEI Plate (30 - 35 ℃)	No glue required	Not required	Required	< 200 mm/s	220 - 240 ℃	50% - 100%	N/A
TPU for AMS	N/A	N/A	N/A	19.0 kJ/m²	N/A	1.20%	63 D	36%	16.9 MPa	N/A	Required	Blast Drying Oven: 70 ℃, 8 h Printer Heatbed (Covered, Flip midway): 80 - 90 ℃, 12 h	✔	0.4 / 0.6 / 0.8 mm Hardened Steel / Stainless Steel	Smooth PEI Plate (30 - 35 ℃) Textured PEI Plate (30 - 35 ℃)	No glue required	Not required	Required	< 250 mm/s	220 - 240 ℃	20% - 50%	N/A
PET-CF	36.0 kJ/m²	131 MPa	5320 MPa	4.5 kJ/m²	205 ℃	0.37%	N/A	N/A	N/A	N/A	Required	Blast Drying Oven: 80 ℃, 8 - 12 h Printer Heatbed (Covered, Flip midway): 90 - 100 ℃, 12 h		0.4 / 0.6 (recommended) / 0.8 mm Hardened Steel	Smooth PEI Plate (70 - 100 ℃) Textured PEI Plate (70 - 100 ℃) Cool Plate SuperTack (60 - 80 ℃)	Bambu Glue Stick required	Required	Required	< 100 mm/s	260 - 300 ℃	0 - 40%	90 - 130 ℃ 6 - 12 hours
PAHT-CF	57.5 kJ/m²	125 MPa	4230 MPa	13.3 kJ/m²	194 ℃	0.88%	N/A	N/A	N/A	N/A	Required	Blast Drying Oven: 80 ℃, 8 - 12 h Printer Heatbed (Covered, Flip midway): 90 - 100 ℃, 12 h	✔	0.4 / 0.6 (recommended) / 0.8 mm Hardened Steel	Smooth PEI Plate (100 - 120 ℃) Textured PEI Plate (100 - 120 ℃)	Bambu Glue Stick required	Required	Required	< 100 mm/s	260 - 300 ℃	0 - 40%	90 - 130 ℃ 6 - 12 hours
PA6-CF	40.3 kJ/m²	151 MPa	5460 MPa	15.5 kJ/m²	186 ℃	2.35%	N/A	N/A	N/A	N/A	Required	Blast Drying Oven: 80 ℃, 8 - 12 h Printer Heatbed (Covered, Flip midway): 90 - 100 ℃, 12 h		0.4 / 0.6 (recommended) / 0.8 mm Hardened Steel	Smooth PEI Plate (100 - 120 ℃) Textured PEI Plate (100 - 120 ℃)	Bambu Glue Stick required	Required	Required	< 100 mm/s	260 - 300 ℃	0 - 40%	90 - 130 ℃ 6 - 12 hours
PA6-GF	27.2 kJ/m²	120 MPa	3670 MPa	4.1 kJ/m²	182 ℃	2.56%	N/A	N/A	N/A	N/A	Required	Blast Drying Oven: 80 ℃, 8 - 12 h Printer Heatbed (Covered, Flip midway): 90 - 100 ℃, 12 h	✔	0.4 / 0.6 (recommended) / 0.8 mm Hardened Steel	Smooth PEI Plate (100 - 120 ℃) Textured PEI Plate (100 - 120 ℃)	Bambu Glue Stick required	Required	Required	< 130 mm/s	260 - 290 ℃	0 - 40%	90 - 130 ℃ 6 - 12 hours
PPS-CF	27.8 kJ/m²	142 MPa	7160 MPa	2.8 kJ/m²	264 ℃	0.05%	N/A	N/A	N/A	N/A	Required	Blast Drying Oven: 100 - 140 ℃, 8 - 12 h (within this range, a higher temp, a better drying result) Printer Heatbed (Covered, Flip midway): 110 - 120 ℃, 12 h (not as good as a blast drying oven)		0.4 / 0.6 (recommended) / 0.8 mm Hardened Steel	Smooth PEI Plate (100 - 120 ℃) Textured PEI Plate (100 - 120 ℃)	Bambu Glue Stick required	Required	Required	< 100 mm/s	310 - 340 ℃	0 - 40%	180 - 220 ℃ 6 - 12 hours
PPA-CF	41.7 kJ/m²	208 MPa	9860 MPa	4.3 kJ/m²	227 ℃	1.30%	N/A	N/A	N/A	N/A	Required	Blast Drying Oven: 100 - 140 ℃, 8 - 12 h (within this range, a higher temp, a better drying result) Printer Heatbed (Covered, Flip midway): 110 - 120 ℃, 12 h		0.4 / 0.6 (recommended) / 0.8 mm Hardened Steel	Smooth PEI Plate (100 - 120 ℃) Textured PEI Plate (100 - 120 ℃)	Bambu Glue Stick required	Required	Required	< 100 mm/s	280 - 310 ℃	0 - 40%	120 - 140 ℃ 6 - 12 hours